MSKSEMI 美森科













ESD

15

155

MOV

GDI

PLED

M28S

Product specification





FEATURES

- Excellent h_{FE} Linearity
- High DC Current Gain

Reference News

PACKAGE OUTLINE	Foot position analysis	Marking
A STEEL SERVICE SERVIC	 BASE EMITTER COLLECTOR 	28S
SOT-23		

CLASSIFICATION OF hFE(2)

RANK	В	С	D
RANGE	300 –550	500 –700	650 – 1000



MAXIMUM RATINGS (Ta=25 $^{\circ}$ C unless otherwise noted)

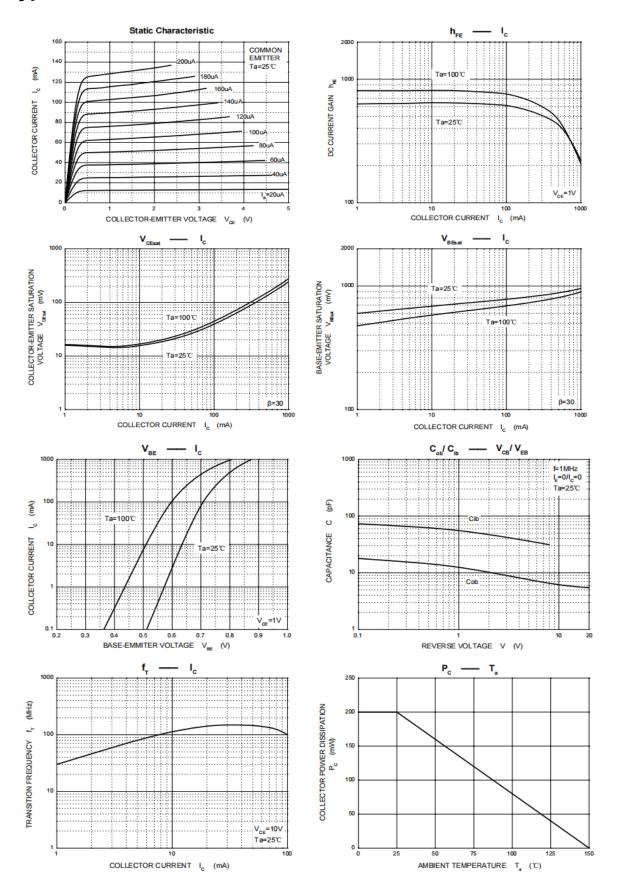
Symbol	Parameter	Value	Unit
V _{СВО}	Collector-Base Voltage	40	٧
V _{CEO}	Collector-Emitter Voltage	20	٧
V _{EBO}	Emitter-Base Voltage	6	٧
lc	Collector Current	1	Α
Pc	Collector Power Dissipation	200	W
Roja	Thermal Resistance From Junction To Ambient	625	°C/W
Tj	Junction Temperature	150	$^{\circ}$
T _{stg}	Storage Temperature	-55~+150	$^{\circ}$

ELECTRICAL CHARACTERISTICS (Ta=25℃ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =0.1mA, I _E =0	40			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =1mA, I _B =0	20			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =0. 1mA, I _C =0	6			٧
Collector cut-off current	I _{CBO}	V _{CB} =35V, I _E =0			0.1	А
Collector cut-off current	Iceo	V _{CE} =20V, I _B =0			5	Α
Emitter cut-off current	I _{EBO}	V _{EB} =5V, I _C =0			0.1	Α
DC current gain	FE(1)	V _{CE} =1V, I _C =1mA	290			
	FE(2)	V _{CE} =1V, I _C =100mA	300		1000	
	FE(3)	V _{CE} =1V, I _C =300mA	300			
	FE(4)	V _{CE} =1V, I _C =500mA	300			
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =600mA, I _B =20mA			0.55	V
Transition frequency	т	V _{CE} =10V,I _E =50mA, f=1MHz	100			MHz
Collector output capacitance	Cob	V _{CB} =10V, I _E =0, f=1MHz		9		pF

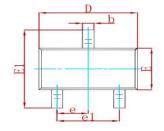


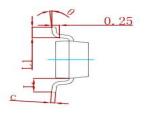
Typical Characteristics

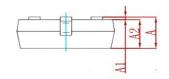




PACKAGE MECHANICAL DATA

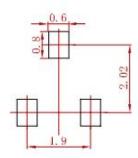






Comple el	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min	Max	Min	Max
Α	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
С	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
е	0.950 TYP		0.03	7 TYP
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022	2 REF
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
M28S	SOT-23	3000



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